Express Mail No.: ET693515625US Docket No.: JP920010068US1 06-14-2002 FORM PTO-1595 (Modified) U.S. DEPARTMENT OF COMMERCE (Rev. 03-01) Patent and Trademark Office OMB No. 0651-0027 (axp.5/31/2002) P08/REV03 102123620 Tab settings - + To the Honorable Commissioner of Pate... Tragemarks: Please record the attached original documents or cop 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): 6-4-62 Yutaka Tsukada Kimihiro Yamanaka Name: International Business Machines Corporation Internal Address: ☐ Yes 🏻 No Additional names(s) of conveying party(ies) 3. Nature of conveyance: Street Address: New Orchard Road ■ Assignment □ Merger ☐ Security Agreement ☐ Change of Name \_\_\_\_ State: NY ZIP: 10504 City: Armonk Other Execution Date: \_\_5/27/02 **⊠** No 4. Application number(s) or patent numbers(s): 10162830 If this document is being filed together with a new application, the execution date of the application is: 5/27/02 A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached? ☐ Yes **⊠** No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: concerning document should be mailed: Name: Lawrence R. Fraley 7. Total fee (37 CFR 3.41):....\$ 40.00 Internal Address: ☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account 00000038 090457 10162830 6/14/2002 TDIAZ1 1 FC:581 40.00 CH Authorized to be charged to deposit account 8. Deposit account number: Street Address: IBM Corporation, IP Law N50/040-4, 09-0457 1701 North Street (Attach duplicate copy of this page if paying by deposit account) City: Endicott State: **NY** ZIP: 13760 DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy

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Lawrence R. Fraley, Reg. No. 26,885

Name of Person Signing

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~ 4, zooz

Date

**REEL: 012975 FRAME: 0673** 

IBM Docket No.: JP920010068US1

## **ASSIGNMENT**

## Whereas, we

Inventor (1) Yutaka Tsukada City of Kouga-gun, Shiga-ken and City County of -and State of Japan and (2) Kimihiro Yamanaka City of Kouga-gun, Shiga-ken Japan County of -and State of Japan and City of County of and State of and City of County of and State of

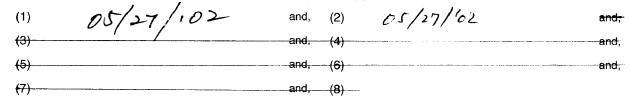
have invented certain improvements in

BALL GRID ARRAY MODULE AND METHOD OF MANUFACTURING SAME

Dates That Inventors Signed the Declaration

Title

and have executed, respectively, a United States patent application therefor on



Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(Signatures of Inventors on Page 2)

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ASSIGNMENT (Continued)		
Title	BALL GRID ARRAY MODULE AND METHOD OF M	IANUFACTURING SAME
City Date	(1) Signed at Yasu, Japan on OS 27	Gignatule of Inventor)  Yutaka Tsukada  (Typed Name of Inventor)
City Date	(2) Signed at Yasu, Japan on OS/27/02	Cimilare Jananaka (Signature of Infentor)  Kimihiro Yamanaka (Typed Name of Inventor)
City Date	(3) Signed at on	(Signature of Inventor)
City Date	(4) Signed at on	(Typed Name of Inventor)  (Signature of Inventor)
City Date	(5) Signed at on	(Typed Name of Inventor)  (Signature of Inventor)
City Date	(6) Signed at on	(Typed Name of Inventor)  (Signature of Inventor)
City Date	(7) Signed at on	(Typed Name of Inventor)  (Signature of Inventor)
City Date	(8) Signed at on	(Typed Name of Inventor)  (Signature of Inventor)
		(Typed Name of Inventor)

**RECORDED: 06/04/2002** 

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